

# G4L3-SD1-LAX3

HPC/AI Server - 5th/4th Gen Intel® Xeon® Scalable -  
4U DP NVIDIA HGX™ H200 DLC



### Key Features

- Liquid-cooled NVIDIA HGX™ H200
- CPU+GPU direct liquid cooling solution with leak detection
- 900GB/s GPU-to-GPU bandwidth with NVIDIA NVLink™ and NVSwitch™
- Dual 5th/4th Gen Intel® Xeon® Scalable Processors
- Dual Intel® Xeon® CPU Max Series
- 8-Channel DDR5 RDIMM, 32 x DIMMs
- Compatible with NVIDIA® BlueField®-3 DPUs and NVIDIA ConnectX®-7 NICs
- 2 x 10Gb/s LAN ports via Intel® X710-AT2
- 2 x M.2 slots with PCIe Gen3 x2 and x1 interface
- 8 x 2.5" Gen5 NVMe/SATA hot-swap bays
- 4 x FHHL dual-slot PCIe Gen5 x16 slots
- 8 x FHHL single-slot PCIe Gen5 x16 slots
- 4+4 3000W 80 PLUS Titanium redundant power supplies

### Specification

Dimensions	4U (W447 x H175.5 x D901 mm)	Modular GPU	Liquid-cooled NVIDIA HGX™ H200 with 8 x SXM GPUs
Motherboard	MSB3-PE0	PCIe Expansion Slots	4 x FHHL dual-slot PCIe Gen5 x16 8 x FHHL single-slot PCIe Gen5 x16  *The ambient temperature is limited to 30°C when NVIDIA® BlueField®-3 DPUs/SuperNIC™ are installed.
CPU	5th/4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Dual processor, TDP up to 385W	I/O Ports	Front: 2 x USB 3.2 Gen1, 1 x VGA, 2 x RJ45, 1 x MLAN (default) Rear: 1 x MLAN
OS Compatibility	<a href="#">OS Support List</a>	Backplane Board	PCIe Gen5 x4 or SATA 6Gb/s
Socket	2 x LGA 4677 (Socket E)	TPM	1 x TPM header (SPI), Optional TPM2.0 kit: CTM012
Chipset	Intel® C741	Power Supply	4+4 3000W 80 PLUS Titanium redundant power supplies AC Input: 115-240V  *The system power supply requires C19 power cord.
Memory	8-Channel DDR5 RDIMM, 32 x DIMMs [5th Gen Intel Xeon] Up to 5600 MT/s, 4400 MT/s [4th Gen Intel Xeon] Up to 4800 MT/s, 4400 MT/s [Intel Xeon Max Series] Up to 4800 MT/s, 4400 MT/s	System Fans	Motherboard: 2 x 60x60x56mm / 2 x 60x60x76mm PCIe slots: 4 x 80x80x56mm GPU tray: 4 x 60x60x38mm
LAN	Front: 2 x 10Gb/s LAN (1 x Intel® X710-AT2), Support NCSI 1 x 10/100/1000 Mbps Management LAN Rear: 1 x 10/100/1000 Mbps Management LAN	Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)  *To ensure system stability and prevent condensation, when the relative humidity exceeds 50%, the coolant inlet temperature must be higher than the dry-bulb temperature and it should not exceed 45°C.
Video	Integrated in ASPEED® AST2600 - 1 x VGA port	Packaging Content	1 x G4L3-SD1-LAX3 6 x Carriers 1 x L-shape Rail kit
Storage	Front hot-swap: 8 x 2.5" Gen5 NVMe/SATA Internal M.2: 1 x M.2 (2280/22110), PCIe Gen3 x2 1 x M.2 (2280/22110), PCIe Gen3 x1	Ordering Part Numbers	6NG4L3SD1DR000LBX3*
RAID	Intel® SATA RAID 0/1/10/5		



Learn more at: <https://www.gigabyte.com/Enterprise>  
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